

IN THE CLAIMS:

Please amend the claims as indicated below.

9. (Original) The method of claim 8, further comprising the step of providing a tip/ring connector for interfacing with said telephone line.
- 5 10. (Original) The method of claim 8, further comprising the step of connecting to a tip/ring connector.
11. (Original) The method of claim 8, wherein said carrier assembly is a motherboard.
- 10 12. (Original) The method of claim 8, further comprising the step of soldering said one or more solder pads to corresponding one or more solder pads on said carrier assembly.
13. (Original) The method of claim 8, further comprising the step of fabricating said modem assembly on a printed circuit board.
- 15 14. (Currently Amended) A printed circuit board, comprising:
  - modem circuitry for interfacing with a telephone line; and
  - one or more solder pads for connecting a signal line of said modem circuitry to a carrier assembly.
- 20 15. (Original) The printed circuit board of claim 14, further comprising a tip/ring connector for interfacing with said telephone line.
- 25 16. (Original) The printed circuit board of claim 14, further comprising a connection to a tip/ring connector.
17. (Original) The printed circuit board of claim 14, wherein said carrier assembly is a motherboard.
- 30 18. (Original) The printed circuit board of claim 14, wherein said one or more solder pads are soldered to corresponding one or more solder pads on said carrier assembly.

19. (Original) The printed circuit board of claim 14, wherein said modem assembly is fabricated on a printed circuit board.
- 5 20. (Original) The printed circuit board of claim 14, wherein said modem assembly is an integrated device.